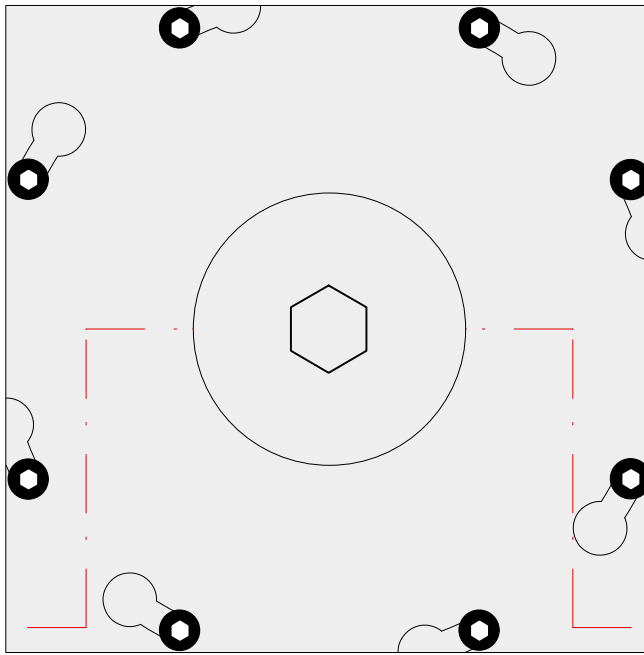


SBT BGA Socket - Direct mount, solderless

Top View

36.225mm

A



36.225mm

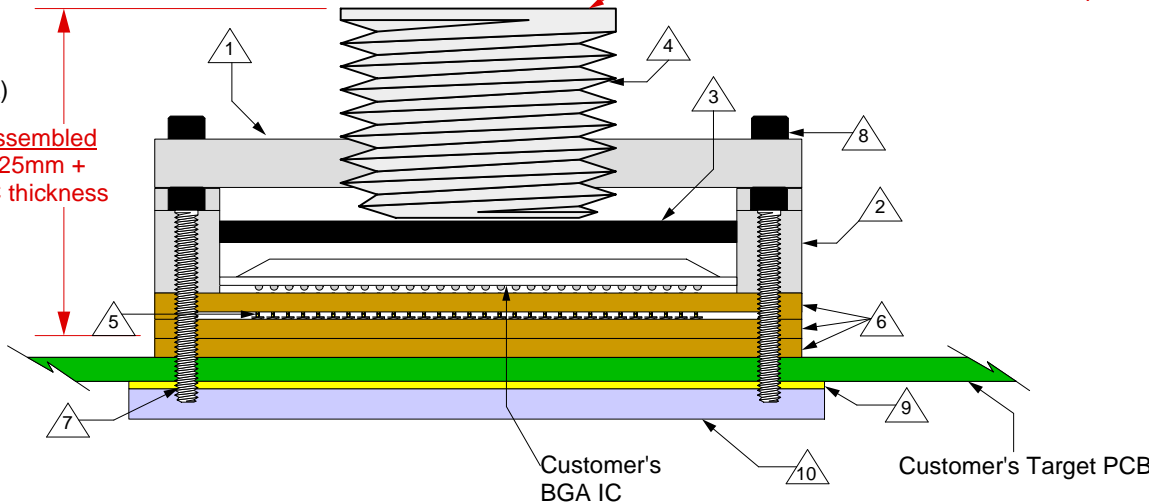
Features

- Wide temperature range (-55C to +180C)
- High current capability (up to 8A)
- Excellent signal integrity at high frequencies
- Low and stable contact resistance for reliable production yield
- Highly compliant to accommodate wide co-planarity variations
- Automated probe manufacturing enables low cost and short lead time

Side View
(Section AA)

Assembled
8.25mm +
IC thickness

Recommended torque = 18 in lbs.



- | | |
|----|---|
| 1 | Socket Lid: Nickel Plated Aluminum.
Thickness = 2.5mm. |
| 2 | Socket base: Nickel Plated Aluminum.
Thickness = 5mm. |
| 3 | Compression Plate: Nickel Plated Aluminum.
Thickness = 2.5mm. |
| 4 | Compression screw: Nickel Plated Aluminum.
Thickness = 5mm, Hex socket = 5mm. |
| 5 | SBT pin: Stamped contact BeCu, Au plated
Spring: SS, Au plated |
| 6 | Pin Guide: Ceramic Filled Peek |
| 7 | Socket base screw: Socket head cap, alloy steel with
black oxide finish, 0-80 fine thread , 12.7mm long. |
| 8 | Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine
thread. |
| 9 | Insulation Plate: FR4/G10, Thickness = 1.59mm. |
| 10 | Backing Plate: Nickel Plated Aluminum.
Thickness = 6.35mm. |

SBT-BGA-6014 Drawing

Status: Released

Scale: -

Rev: A

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Tele: (800) 404-0204
www.ironwoodelectronics.com

Drawing: E Smolentseva

Date: 09/08/2012

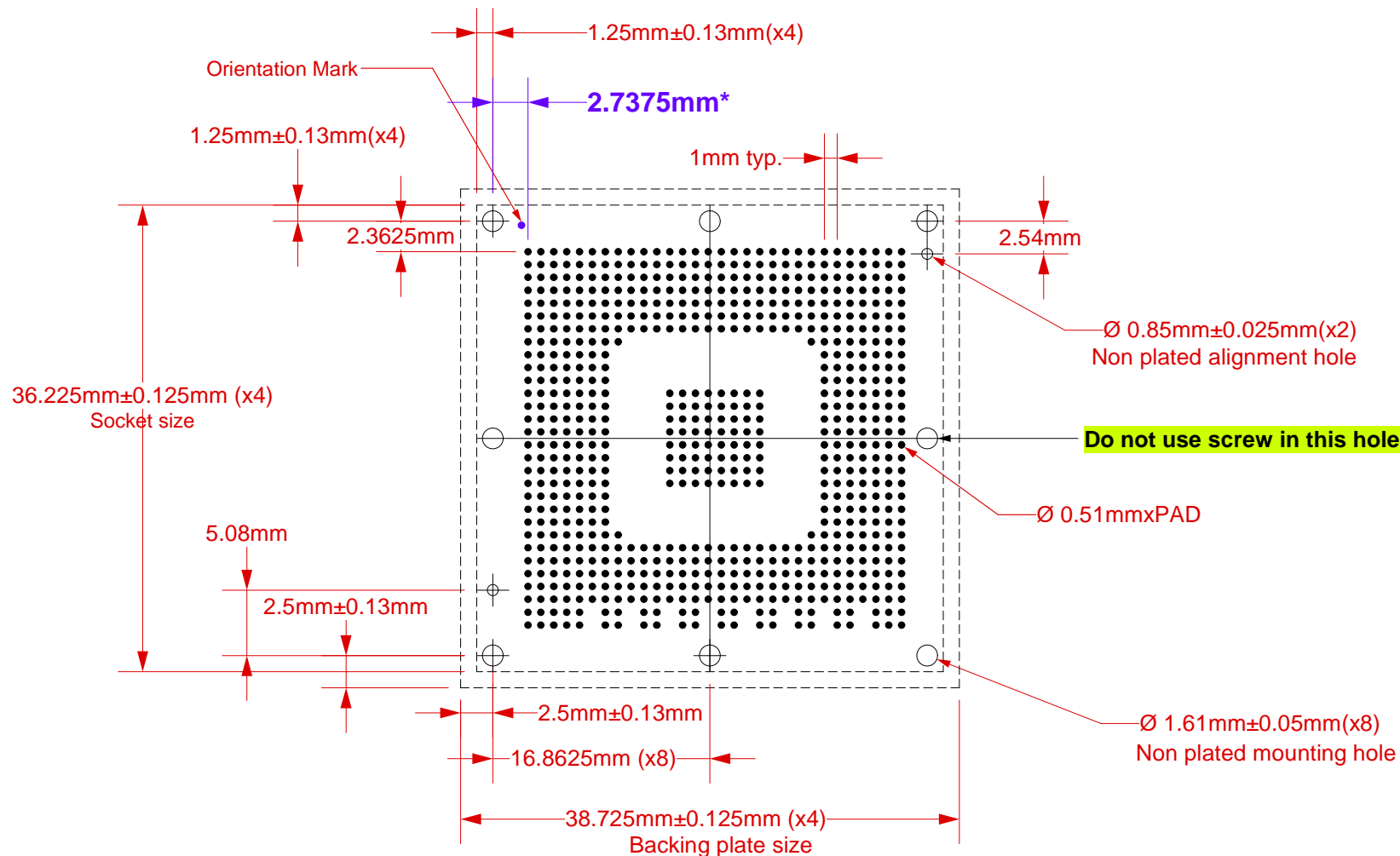
File: SBT-BGA-6014 Dwg.mcd

Modified:

All tolerances: ± 0.125 mm (unless stated otherwise). Materials and specifications are subject to change without notice.

PAGE 1 of 4

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**



Target PCB Recommendations


Total thickness: 2.4mm min.

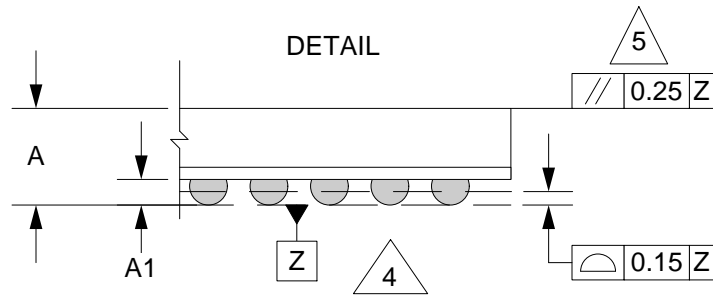
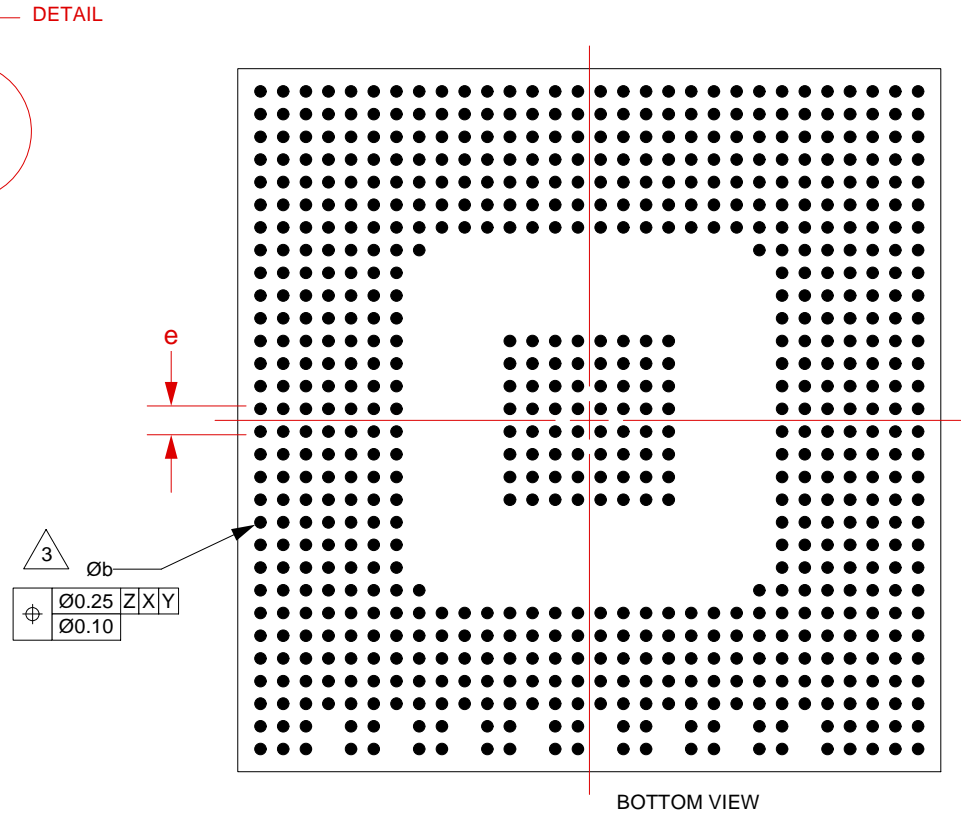
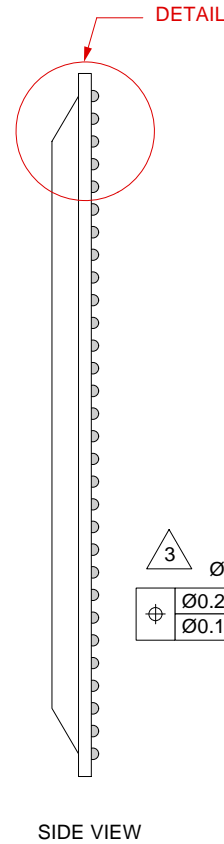
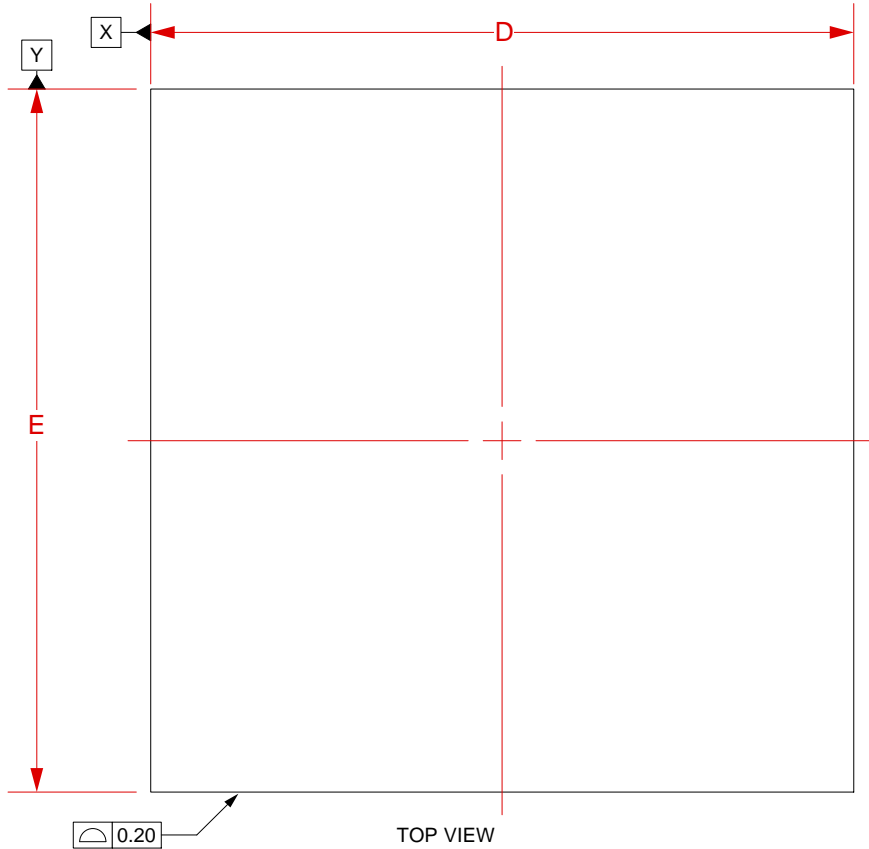
Plating: Gold or Solder finish

PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: $\pm 0.025\text{mm}$ [$\pm 0.001''$] unless stated otherwise.


SBT-BGA-6014 Drawing		Status: Released	Scale: -	Rev: A
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	File: SBT-BGA-6014 Dwg.mcd		Modified:	

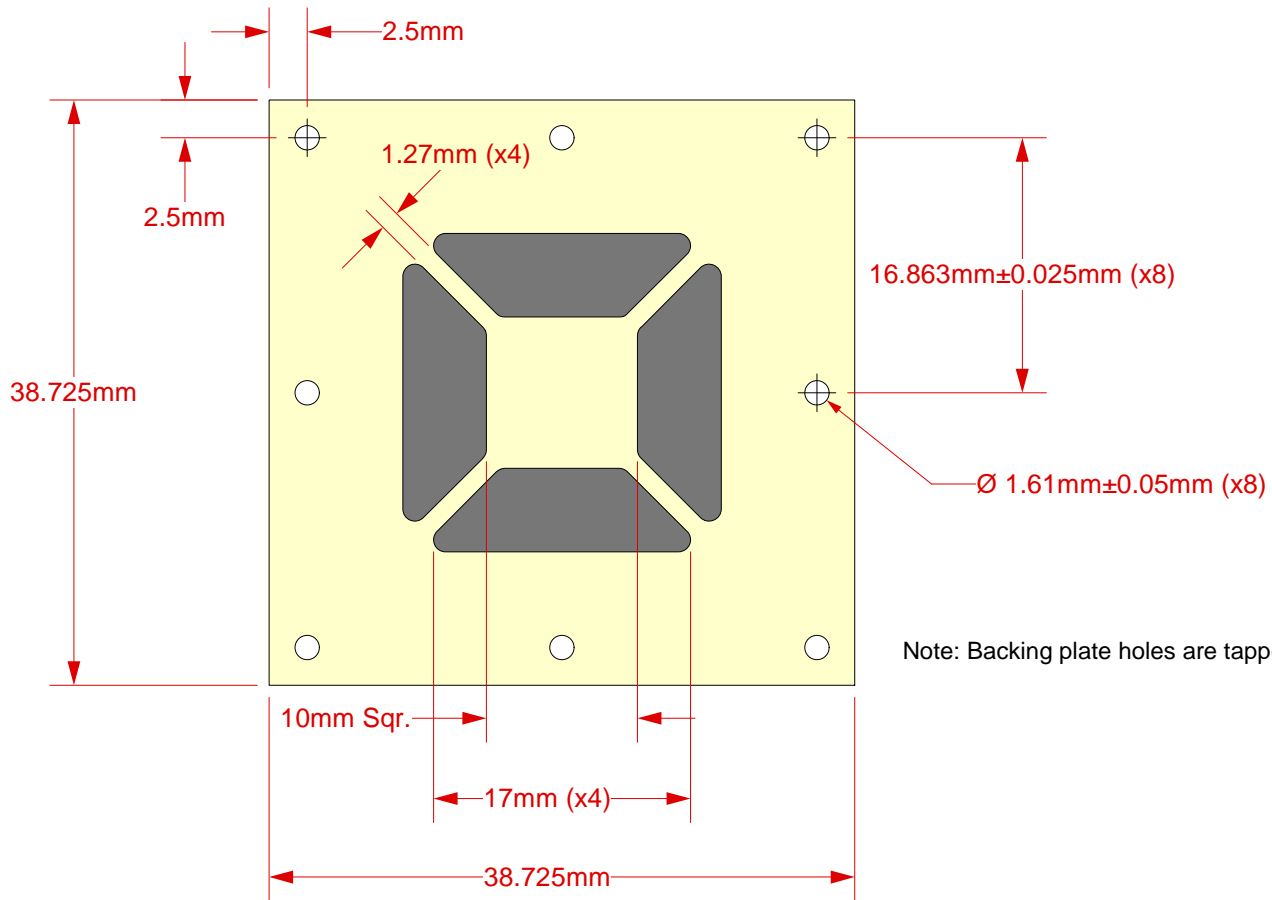


1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 - 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.43
A1	0.4	0.6
b		0.7
D	31.00 BSC	
E	31.00 BSC	
e	1.0 BSC	

Array 30x30

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	Drawing: E Smolentseva		Date: 09/08/2012	
	File: SBT-BGA-6014 Dwg.mcd		Modified:	




Note: Backing plate holes are tapped to accept 0-80 screws.

Top View



Description: Insulation Plate and Backing Plate

SBT-BGA-6014 Drawing		Status: Released	Scale: -	Rev: A
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	File: SBT-BGA-6014 Dwg.mcd		Modified:	